



SOT1353-1

plastic surface-mounted package (TSOP6); 6 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSOP6
Package type industry code	TSOP6
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-74
Mounting method type	S (surface mount)
Issue date	18-4-2013

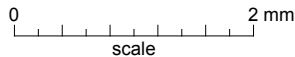
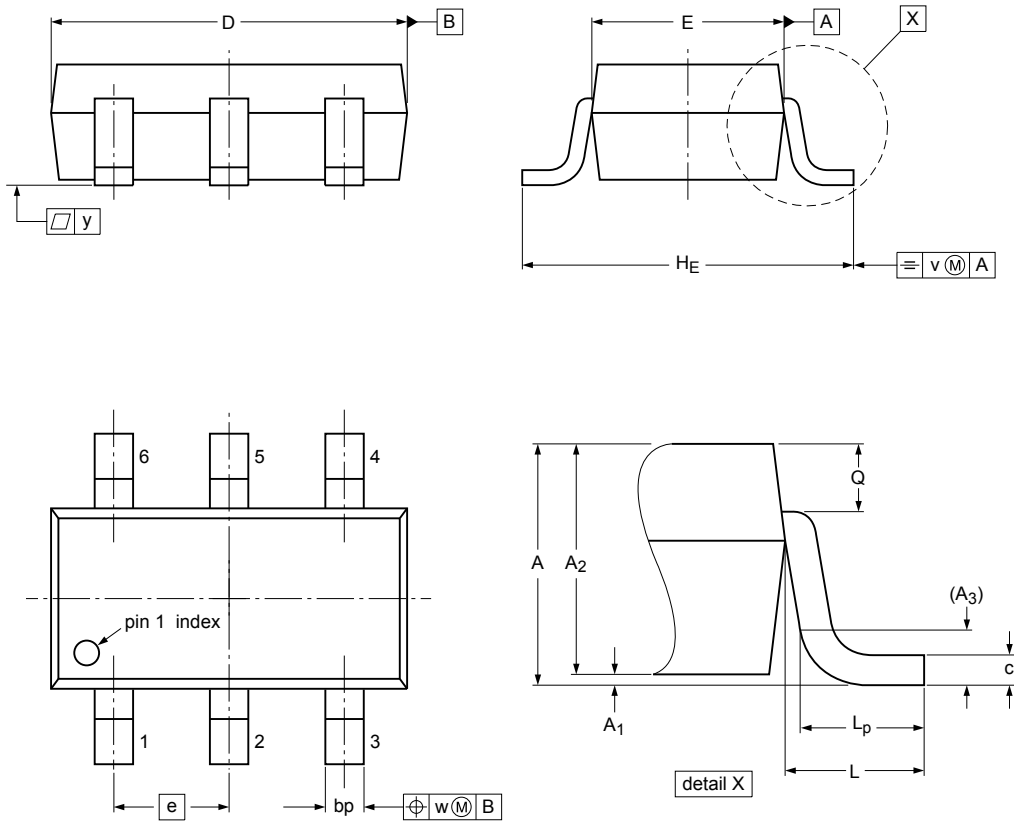
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.7	-	2.9	3.1	mm
E	package width	1.3	-	1.5	1.7	mm
A	seated height	0.9	-	1	1.1	mm
A ₂	package height	0.9	-	1	1.1	mm
e	nominal pitch	-	-	0.95	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

TSOP6: Plastic thin small outline package; 6 leads SOT1353-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D	E	e	H _E	L	L _p	Q	v	w	y
max	1.1	0.1	1.0		0.40	0.26	3.1	1.7		3.0		0.6	0.33			
nom				0.23					0.95		0.58			0.2	0.2	0.1
min	0.9	0.013	0.9		0.25	0.10	2.7	1.3		2.5		0.2	0.23			

sot1353-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1353-1	---	---	SC-74		-13-03-20- 13-04-18

Fig. 1. Package outline TSOP6 (SOT1353-1)

3. Soldering

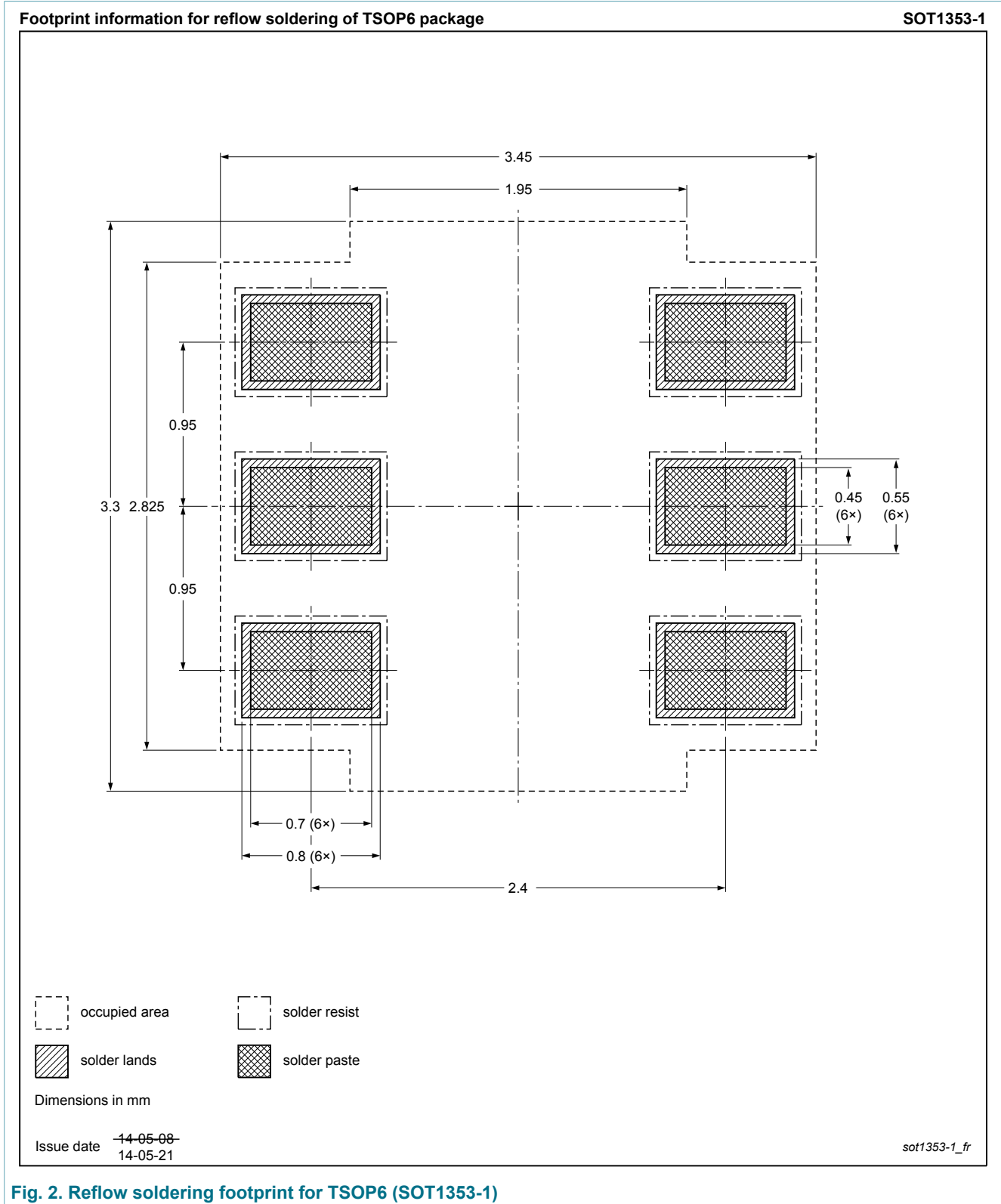


Fig. 2. Reflow soldering footprint for TSOP6 (SOT1353-1)

4. Legal information

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